



05-13-2010

S. DEPARTMENT OF COMMERCE
States Patent and Trademark Office



103597115

To the Director of the U.S. Patent and Trademark Office

or the new address(es) below.

1. Name of conveying party(ies):

Kirio Masui (03/31/2010), Shinpei Hirano
(03/31/2010), Yasuaki Isonaga (04/05/2010), and
Soichi Tanaka (04/05/2010)

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

- ☒ Assignment ☐ Merger ☐ Change of Name
☐ Security Agreement ☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: Sony Corporation

Internal Address: _____

Street Address: _____

1-7-1 Konan
Minato-Ku,

City: Tokyo

State: _____

Country: JAPAN Zip: 108-0075

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)

29/347,523

☐ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name:

RADER, FISHMAN & GRAUER PLLC

Internal Address: Atty. Dkt.: SDE-2479

Street Address: 1233 20th Street, N.W.
Suite 501

City: Washington

State: DC Zip: 20036

Phone Number: (202) 955-3750

Fax Number: (202) 955-3751

Email Address: _____

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

Deposit Account Number 18-0013

Authorized User Name Sterling D. Fillmore

9. Signature:

Signature

May 10, 2010

Date

Sterling D. Fillmore - 63,796

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

3

05/12/2010 NCAMA1 00000024 100013 89347523
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

COMPUTER

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **SONY CORPORATION**, a Japanese corporation with offices at **1-7-1 Konan, Minato-ku, Tokyo, 108-0075 JAPAN**, (hereinafter referenced as **ASSIGNEES**) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of Ten Dollar (\$10.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said **ASSIGNEES**, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said **ASSIGNEES**, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of **ASSIGNEES** or its designee, as **ASSIGNEES** or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

PATENT**REEL: 024383 FRAME: 0721**

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 29/347,523, Filing Date: 02/19/2010.

This assignment executed on the dates indicated below.

Kirio MASUI	<u>Kirio Masui</u>	<u>March 31, 2010</u>
	Signature	Date
Shinpei HIRANO	<u>Shinpei Hirano</u>	<u>March 31, 2010</u>
	Signature	Date
Yasuaki ISONAGA	<u>Yasuaki Isonaga</u>	<u>April 5, 2010</u>
	Signature	Date
Soichi TANAKA	<u>Soichi Tanaka</u>	<u>April 5, 2010</u>
	Signature	Date

PATENT

RECORDED: 05/10/2010

REEL: 024383 FRAME: 0722